Panasonic

OEM Manual

3-inch Compact Floppy Disk Drive

EME-150 / 250



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1. General

<u>.</u>

EME-150 (Single-sided) and EME-250 (Double-sided) are the compact floppy disk drives which drive 3-inch compact floppy disk (80mm wide, 100mm long and 5mm thick) as a new standard system in this field.

The size of these disk drives is 90mm wide, 150mm deep and 35 mm high, and it can be easily rested on your palm. Despite the compact size, EME-150 and EME-250 provide the capacity of 250K and 500K bytes equivalent to 5.25-inch floppy disk drives.

<Features>

Compatible with 5.25 inch disk drives.

Your controller can be used with the compact floppy disk drive as it is because the recording method, data transfer rate and disk rotation speed are the same as those of 5.25-inch floopy disk drives.

Low Power Consumption.

Low Profile and Light in Weight

One-touch loading/ejecting mechanism

A pocket-size compact floppy disk with a hard case and automatic head window shutters.

A one-touch loading mechanism is adopted for loading/ejecting a floppy disk into/from the drive.

Easy to use

- 1) The media is protected by a rigid hard shell giving increased durability and providing the facility for labelling with a ball point pen.
- 2) A head window shutter provides protection of the disk surface and is automatically opened and closed when the disk is inserted or withdrawn from the drive.
- 3) A simple one touch "write protect" mechanism prevents accidental writing on pre-recorded disks.
- 4) Up to two drives can be connected in daisy chain.
- 5) An IN USE display lamp is fitted and is controlled by DRIVE SELECT signal.

Long-life and reliable disk

The plastic center hub of the disk increases the reliability and life of the disk.

This feature combined with the internal cleaning liner within the case ensures consistent rotation and perfect alignment with heads.

2. Specification Summary

2.1 Performance

2.1.1 Performance Specifications of EME-150 (Single head)

Encoding Method	FM	MFM	
Recording Capacity (Unformatted) Single side Double side Per track	Single Density 125K Byte 3125 Byte	Double Density 250K Byte	
(Formatted) Byte/Sector(Byte) Sector/Track Single side(Byte) Double side(Byte) Per track(Byte)	128 256 512 16 9 5 82K 92K 102K 164K 184K 205K 2048 2304 2560	6250 Byte 256 512 1024 16 9 5 164K 184K 204K 328K 369K 410K 4096 4608 5120	
Transfer rate	125K bits/sec.	250K bits/sec.	
Latency (average)	100ms	ec.	
Access time Track to track Average Settling time Motor start	12msec. 171msec. 15msec. 1.0sec.max.		
Index	1		
Rotational Speed	300r	pm	
Max. recording density	4473bpi	8946bpi	
Track density	100tpi		
Number of tracks	40		
Mechanical dimensions Height Width Depth Weight	35 mm (1. 90 mm (3. 150 mm (5. 460 g	5")	

Table 1-1.

2.1.2 Performance Specifications of EME-250 (Double head)

Encoding Method	FM	MFM	
Recording Capacity (Unformatted) Single side Double side Per track	Single Density 250K Byte 3125 Byte	Double Density 500K Byte 6250 Byte	
(Formatted) Byte/Sector(Byte) Sector/Track Single side(Byte) Double side(Byte) Per track(Byte)	128 256 512 16 9 5 82K 92K 102K 164K 184K 205K 2048 2304 2560	256 512 1024 16 9 5 164K 184K 204K 328K 369K 410K 4096 4608 5120	
Transfer rate	125K bits/sec.	250K bits/sec.	
Latency (average)	100ms	ec.	
Access time Track to track Average Settling time Motor start	12 msec. 171 msec. 15 msec. 1. Csec. max.		
Index	1		
Rotational Speed	300r	pm	
Max. recording density	4915bpi	9830bpi	
Track density	, 100t	pi	
Number of tracks	80 (40x	2)	
Mechanical dimensions Height Width Depth Weight	35 mm (1.4 90mm (3.5 150mm (5.9 460 g	")	

Table 1-2.

2.1.3 Power Requirements

	DC Power Supply	. Voltage Deviation	Current Consumption	Ripple
The state of the s	+ 5V +12V	± 5% ± 5%	Typ. 0:22 A 0:30 A	50mVp-p Max. 100mVp-p Max.
Property and the second	Power Consumption	2.5W TYP	. Spir	ve selected adle motor ON STOP

Table 2.

. <u>Mode</u>		Power	Consump	tion
1. Drive selected				
Spindle motor OFF		12 V	0,06A	TYP.
TROO STOP		5 7	0.22A	TTT.
2. Drive selected				
Spindle motor ON		1 2 V	0.121	TTP.
TROO STOP		5 V	0,22A	TTP.
3. Drive selected				
Spindle motor ON		1 2 V	0.30A	TYP.
TR00 ↔ TR39 Serial	seeks	5 V	0.15A	TYP.
(Step Rate msec.)				

2.1.4 Environmental Requirements

Operational

The following shall be applied to the drive in operation as described in Table 3.

Temperature Range: 5°C to 46°C

Humidity Range : 20% to 80% RH without condensa-

tion

Maximum Wet Bulb : 29°C

Table 3. Operational Environments

Non-Operational

In non-operation situation such as during shipping or storage, the following requirements shall be applied to the drive as described in Table 4x

Temperature Range: -25°C to 60°C

Humidity Range : 5% to 95% RH without condensa-

Maximum Wet Bulb : 29°C max. (No condensation)

Table 4. Non-Operational Environments

2.2 Reliability

Reliability requirements for the 3" floppy disk drive shall be as follows:

MTBF	8000 POH *
MTTR	30 minutes
Drive life	5 years
Media life (Rotating)	3 x 106 (Passes per Track)
Insertion	10,000
Error Rates	
Soft Error Rate	1 per 10° bits
Hard Error Rate	1 per 10 ¹² bits
Seek Error Rate	1 per 10 ⁶ seeks.

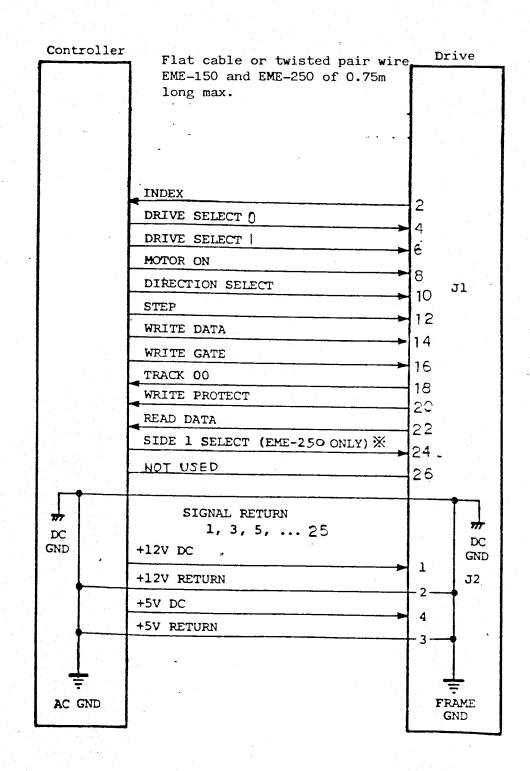
Table 5.

3. Electrical Interface

3.1 Signal Interface Allocation

The assignment of interface signals shall be as shown in Figure 1. The function of each line, signal levels and connectors required are indicated in the following sections.

^{*} Typical operating time of the spindle motor is 25% of POH.



% On SIDE 1 SELECT, EME-150 will be NO USE.

3.1.1 Input Signals

EME-150 and EME-250 shall require the following input signals which are active at "LOW" level:

- (1) DRIVE SELECT 0 to 1
- (2) MOTOR ON
- (3) DIRECTION SELECT
- (4) STEP
- (5) WRITE GATE
- (6) WRITE DATA

(8) SIDE 1 SELECT

These signals have the following electrical specifications.

LOW level	ACTIVE	0V to 0.4V
HIGH level	NO ACTIVE	2.5V to 5.25V
Input in	npedance	$1 ext{K} \Omega$ to pull up to 5V

Table 6. Input Signal Voltage Level

(1) DRIVE SELECT O to 1

Up to two drives can be connected in daisy chain by setting the switch on the printed circuit board. The switch DS 0 to 1 correspond to DRIVE SELECT 0 to .

For example, the drive which short-circuits DS1 can send/receive a data signal only with DRIVE SELECT 1="LOW".

(2) MOTOR ON

The disk drive motor can be activated when this signal is at "LOW" level.

1.0 second is required from the activation until read/write operation.

(3) DIRECTION SELECT

The signal can determine the moving direction of the head when the step pulse is input. The head moves as follows when the step pulse is input:

HIGH level	OUT direction		
	(away from the center of the disk)		
LOW level IN direction			
	(toward the center of the disk)		

Table 7. Step Direction Select Signal

The direction selection shall be made at least lps (min.) before the trailing edge of the step pulse, and held for lps (min.) from the trailing edge of the step pulse.

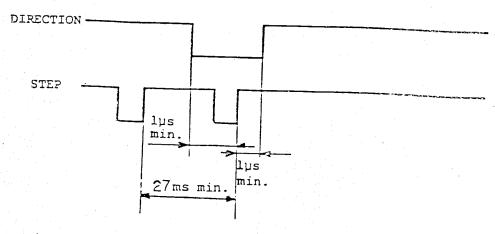


Figure 2. Step Direction Select Signal Ciming

This signal shall shift the head by one track by one pulse in the direction specified by the DIRECTION SELECT signal when the drive is selected. The pulse interval must be 2 ms or more.

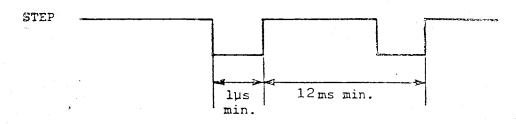


Figure 3. Step Signal

(5) WRITE GATE

Setting this signal at "LOW" level, the drive shall write data on the disk with WRITE PROTECT "OFF" and INDEX period at 200ms+/-2.5%. While the signal is "LOW", the step signal shall not be accepted. Keep the DRIVE SELECT and MOTOR ON signals active because the erase head operates for 1.3ms (EME-250) or 1.7ms (EME-150) from the trailing edge of the WRITE GATE.

(6) WRITE DATA

This enables the head to write data on the disk. Each transition from "HIGH" to "LOW" causes the current through the READ/WRITE head to be reversed thereby writing a data bit. This writing can be performed with the WRITE GATE and INDEX period at 200ms+/-2.5%, and the WRITE PROTECT of CFD cartrige "OFF", and DRIVE SELECT "ON".

Refer to Figure 5. for timing.

(7) SIDE 1 SELECT (EME-250)

At "HIGH" level this signal selects SIDE 0 and at "LOW" level SIDE 1.

3.1.2 Output Signals

EME-150 and EME-250 shall have the following output signals which are active at "LOW" level:

- (1) TRACK 00
- (2) INDEX
- (3) WRITE PROTECT
- (4) READ DATA

These, signals have the following power requirements.

LOW level	ACTIVE	0 to 0.4V (-10 mA)
HIGH level	NO ACTIVE	2.5V to 5.25V (+250 µ A)
		Open collector output

Table 8. Output Signal Voltage Level

All the output signals are at "HIGH" level when the drive is not selected.

(1) TRACK 00

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This signal at "LOW" level indicates that the READ/WRITE head is on the track 00.

(2) INDEX

This is produced each time the index hole is detected by the sensor.

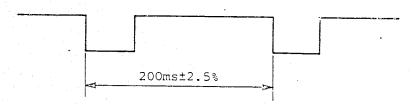


Figure 4. Index Signal

Detection of the INDEX signal shall be made with the leading edge, not with the level.

The signal is at "LOW" level when no CFD cartridge is in the drive.

(3) WRITE PROTECT

This indicates that the write protection of the loaded surface is set.

(4) READ DATA

This provides the "RAW READ" comprising of clock and data bit pulses read by the drive circuit. The signal is output at every detection of data on the disk.

3.1.3 Drive/Receive Circuits

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This drive shall use LSTTL(74LS14)equivalent as an input line receiver and TTL 7438 or equivalent as an output driver.

Figure 5 indicates the recommended interface circuits.

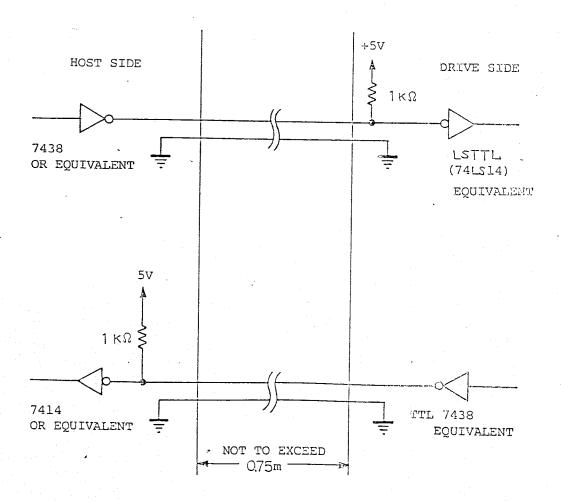
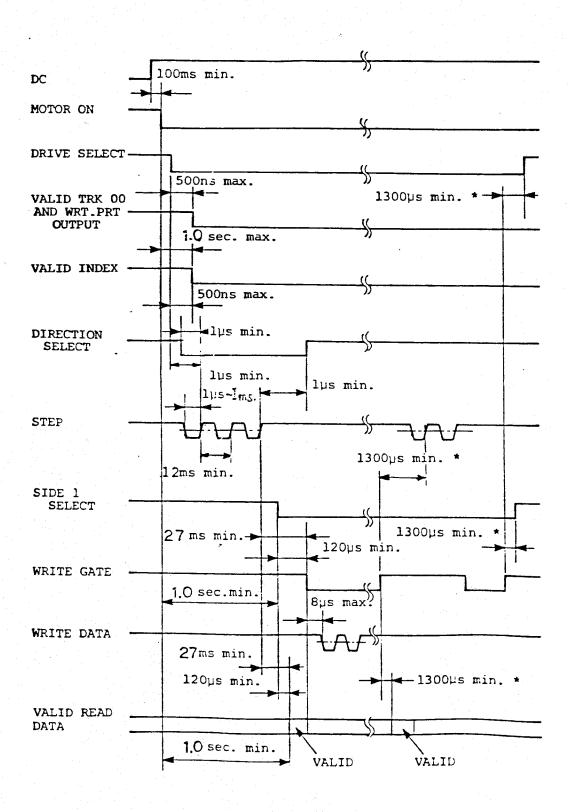


Figure 5.

in C



* in case of EME-150 change to 1700µs min.

Figure 6.

3.2 Power Interface

The drive requires both DC 5V and DC 12V for its operation. Supply each power to P2/J2 connector. The specifications of supply voltages and the pin arrangement of connector are as follows:

J2 Pin No.	Voltage	Tolerance	Ripple
1	DC +12V		
. 2	+12V RETURN	± 5	100mVp-p
3	+ 5V RETURN		
4	DC +5V	±5%	50mVp-p

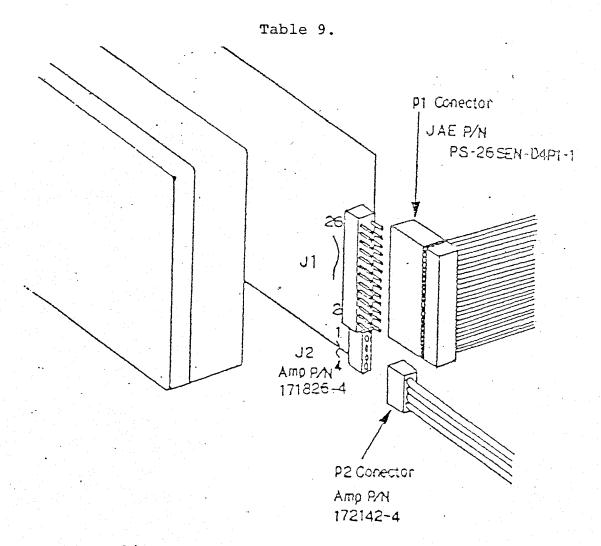


Figure 7. Interface Connectors-Mechanical Location Diagram

4. Mechanical Interface

The electrical interface between the drive and the host system is via a couple of connectors. Jl provides the signal interface and J2 the power.

Figure 7 shows the connector

. 4.1 J1/Pl Connector

position.

The connection to J1 connector is through a 26-pin connector. The pc board side has even numbers and the opposite side odd numbers.

The recommended Pl connectors are shown below,

Manufacturer	Connector
	P/N
JAE	PS-26SEN-D4P1-1
HIROSE	HIF3-26D-254R

4.2 J2/P2 Connector

J2 connector uses a 4-pin AMP P/N 171826-4.

The recommended P2 connectors are shown below.

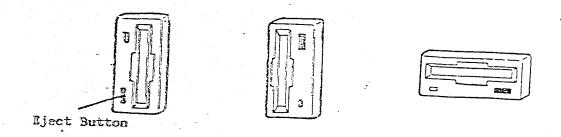
Manufacturer	Connector P/N	Contact P/N
AMP	172142-4	170355-1

Table 11. Recommended P2 Connector

5. Mounting and Drive Dimensions

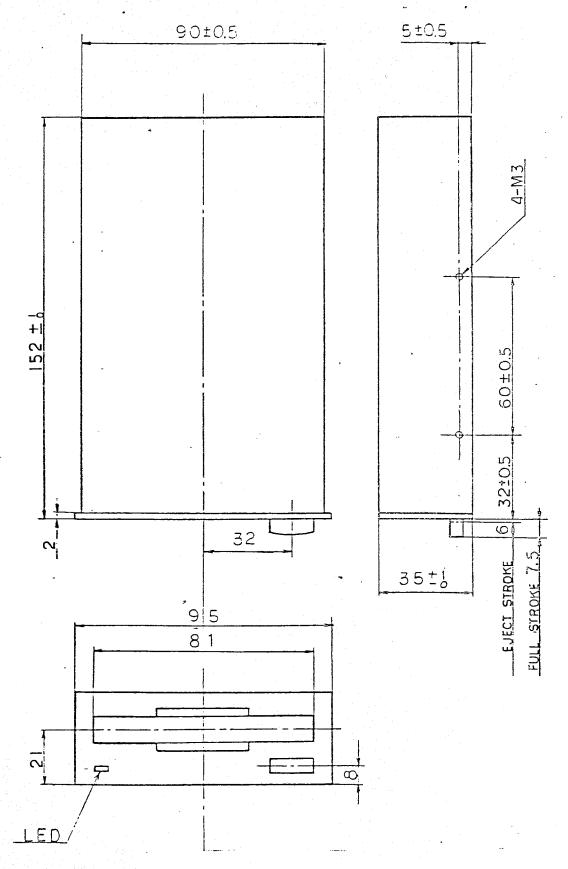
Mounting Recommendations

See Figure



Vertical Type A Vertical Type B Horizontal

Figure 8 . Installation Direction



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Figure 9. Outside Dimensions

5. Precautions for Installation

- 5.1 Set the rise time of the +5V power supply to 300 ms or less for the rising rates between 10 and 90%.
- In installation, keep the drive as far away as possible from noise sources such as switching regulator, CRT monitor and others or take a shielding measure for them against noise.
- When using a flat cable for the wiring material, observe the following rules:

In case of the daisy chain connection, Total wire length $\le 0.75m$

Characteristic impedance: 90 to 110Ω

- When you install two drives close together or install drive(s) in a sealed enclosure, installation of heat radiation holes is recommended to avoid excessive temperature increase mainly due to heat generation of the spindle motor.
- when mounting on the framework, make sure that the framework contact with the drive chassis only at the area of the mounting holes, and that the movable part of the drive mechanism is free from the framework.
- 5.6 In installation, insulate between drive chassis and framework from view point of error rate and noise characteristics.